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Register now at www.smartsystemsintegration.com/conferenceregistration

Conference Fees

	Registration until 19 February 2010	Registration as of 20 February 2010
Full conference	965,00 EUR	995,00 EUR
Full conference university staff and research institutes*	595,00 EUR	695,00 EUR
Full conference students*	290,00 EUR	290,00 EUR
One day ticket	565,00 EUR	595,00 EUR
Conference Dinner	50,00 EUR	50,00 EUR
Pre-Conference Field Trip	50,00 EUR	50,00 EUR

* University staff, research institute staff and students may only register for the full conference at special rates and must enclose a copy of their university/research institute ID-card.

All fees plus 20% Italian VAT.

Registration terms

Registrations are accepted online at www.smartsystemsintegration.com/conference only. Upon receipt of the registration participants will receive a voucher, serving as booking confirmation. For registrations on-site a last-minute-registration fee of 40,00 EUR per person becomes due. Cancellations will be accepted in written form only. If Mesago receives your cancellation until 23 February 2010 a processing fee of 85,00 EUR becomes due. After this date and if the participant does not attend, the full fee becomes due. In case a participant should not be able to attend, a substitute can be nominated. Beyond reimbursement of already paid participation fees additional claims will not be fulfilled. Payment will only be accepted by credit card. The following credit cards are accepted: Eurocard, Visa and American Express. Participation without payment will not be allowed. Program or speakers are subject to change and do not entitle to any claims.

Do you have any questions concerning the registration?

We will be happy to assist you at phone: +49 711 61946-828 or email: janet.sachsenweger@mesago.com.

Organizer:



Mesago Messe Frankfurt GmbH
Rotebuehlstr. 83-85
70178 Stuttgart
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R. Zengerle IMTEK Freiburg, D
G. Q. (Kouchi) Zhang Philips LightLabs, NL

Conference Package

The conference fee includes participation in the conference parts booked, proceedings (CD-ROM), lunch on the days registered, coffee breaks and free admission to the exhibition, the poster session and the special session by EPOSS.

Venue

Spazio Villa Erba
Largo Luchino Visconti, 4
22012 Cernobbio (Como), Italy
www.villaerba.it

Registration on-site

The conference office will open 1 hour before the beginning of the conference. Early check-in on Monday 22 March 2010 12:30 – 15:00

Headquarter Hotel

Hotel Regina Olga
Via Regina, 18, 22012 Cernobbio (Como)
www.hotelreginaolga.it

Book your hotel early in advance!

For more hotels, booking forms and detailed information please see www.smartsystemsintegration.com. Special hotel rates are available until 10 February 2010.

Getting There

There are very well connections to the airports of Milan Malpensa, Linate and Orio al Serio as well as to the airport of Lugano. Of course you can also arrive by car or train. For detailed information please have a look at www.smartsystemsintegration.com/totheevent



SMART SYSTEMS INTEGRATION

These technologies are focused

- microsystems- and nanotechnology
- optics
- fluidics
- sensors and actuators
- chemistry and biology
- medicine
- electronics and
- wireless communication technologies

Speakers and participants from the following industries take part

- automation
- automotive
- aerospace
- logistics
- RF
- life science
- and more...

Pre-Conference Field Trip

The SMART SYSTEMS INTEGRATION 2010 offers again a field trip to a local company on 22 March 2010 in the afternoon. The details will be published shortly at www.smartsystemsintegration.com/conference.

A participation fee will be charged. Registration is required by 28 February 2010.

Spouse Program

You would like to bring your spouse and family to Como? They can join the Spouse Program of SMART SYSTEMS INTEGRATION 2010 which includes guided tours to Como and the participation in the Conference Dinner at Villa Geno directly at the shores of lake Como.

For details and prices please contact us at smart@mesago.com.

Registration is required.

Exhibition

The conference is accompanied by an exhibition.

Visitors can gain free entry to the SMART SYSTEMS INTEGRATION 2010 exhibition by registering at www.smartsystemsintegration.com/registration

Exhibitors

EPOSS European Technology Platform on Smart Systems Integration

EUREKA

EURIPIDES

Fraunhofer Einrichtung für Elektronische Nanosysteme ENAS

Fraunhofer Institut für Photonische Mikrosysteme IPMS

Fraunhofer IZM

Kammrath & Weiss GmbH

Micronarc

Robert Bosch GmbH

Smart Systems Campus

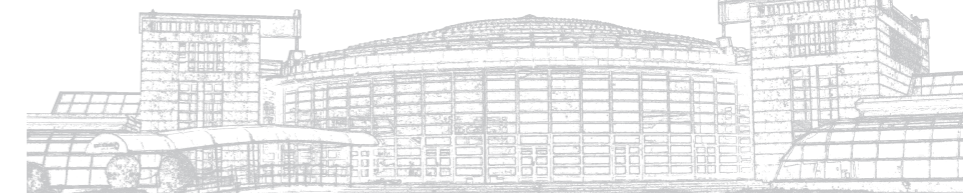
SUSS MicroTec

List as by 17 December 2009.

For the latest exhibitor list please have a look at www.smartsystemsintegration.com/exhibitorlist

Conference Program SMART SYSTEMS INTEGRATION 2010

This is where science and industry meet to merge vision and practice on an international level.



European Conference & Exhibition on Integration Issues of Miniaturized Systems – MEMS, MOEMS, ICs and Electronic Components

Intelligent functions based on micro systems technologies can be found in many applications of everybody's daily life. Mobile phones are called smart phones and are equipped with digital cameras, music players, game consoles and PDAs. Cars are getting more and more intelligent due to self controlled operation and adaptive safety systems. Minimal invasive therapy is inconceivable without micro systems including sensing functions, signal processing and actuators. Smart systems go beyond micro systems for single physical, biological or chemical parameter measurements combined with signal processing and actuating functions. Smart systems integration addresses the demand for miniaturized multifunctional devices and specialized connected and interacting solutions. Multidisciplinary approaches featuring devices for complex solutions and making use of shared and, increasingly, self-organizing resources are among the most ambitious challenges.

Smart systems will be able to take over complex human perceptive and cognitive functions. Smart devices will frequently act unnoticeably in the background and intervene visibly only when human capabilities to act and to react are reduced or cease to exist. Examples for such smart systems and related integration challenges are object recognition devices for automated production systems or devices for monitoring the physical and mental condition of vehicle drivers.

The 4th SMART SYSTEMS INTEGRATION in 2010 addresses application as well as basic aspects and will show a snap shot of the European work on this field. Within the EPOSS session best practice examples will be demonstrated. The MEMUNITY workshop focuses on test and parameter characterization of systems and components. The implementation of printed electronics and functionalities in smart systems will be discussed together with OE-A in the session »Organic and Printed Electronics«.

Prof. Dr. Thomas Gessner
Fraunhofer Research Institution for Electronic Nano Systems, Germany
Conference Chair, SMART SYSTEMS INTEGRATION 2010

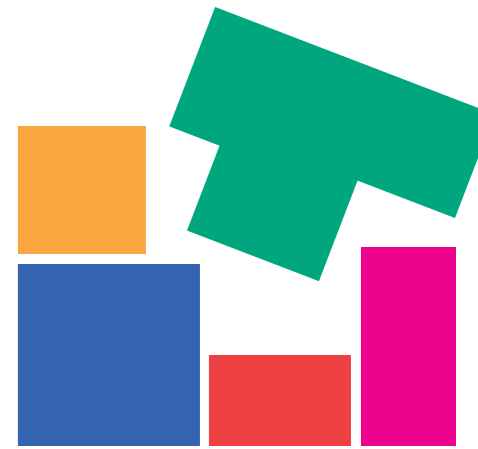
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Part of the activities of:



SMART SYSTEMS INTEGRATION

Como, Italy
23–24 March 2010

Conference Topics:

- Smart Systems for Automotive, Aeronautics and Food Transportation
- Diagnostic and Medical Therapeutic Systems
- Power Management
- Smart Sensornets and Communication Devices
- Technical and Economical Trends
- Design of Smart Systems
- Micro and Nano Materials and Systems
- Advanced Micro and Nano Technologies
- Assembly and Interconnect Technologies
- System Integration and Packaging
- Reliability of Components and Systems
- Organic and Printed Electronics

Keynote Speakers

- Klaus Schymanietz, EADS, D
- Augusto de Albuquerque, EU-Commission, B
- Carmelo Papa, STMicroelectronics, I
- Ryo Imura, Hitachi, J

Tuesday, 23 March 2010

Welcome

8:45 hrs Opening by Thomas Gessner, Fraunhofer ENAS, Conference Chairman, D

Keynote I

9:00 hrs The EPoSS approach to addressing the societal challenges of the future
Klaus Schymanietz, EADS, D

Keynote II

9:20 hrs From microsystems to smart systems: the challenges ahead in EU research
Augusto de Albuquerque, EU-Commission, B

Keynote III

9:40 hrs Smart Systems Integration at STMicroelectronics
Carmelo Papa, STMicroelectronics, I

COFFEE BREAK AND EXHIBITION

Session I

System Integration and Packaging I

Chairmen: Ilkka Suni, VTT Technical Research Centre of Finland, FIN
Carles Cané, Centro Nacional de Microelectронica (CNM-IMB), E

10:20 Heterointegration technologies for multifunctional systems
Klaus-Dieter Lang, Fraunhofer IZM, D

10:45 New approaches in safety technology thanks to function integration/ smart systems integration
Eberhard Klotz, FESTO AG & Co. KG, D

11:10 Polymer Bonded LCP Device Housing Enables Selective Thermal Management for Photonic Device Packages
Andy Longford, PandA Europe, UK

11:35 NEMS/MEMS and passive components integration by using novel LTCC substrate
Jörg Frömel, Fraunhofer ENAS, D

12:00 Embedding sensor systems into modular polymer blocks - 2.5D approach to building smart objects
Maryna Lishchynska, Cork Institute of Technology, IRL

Session III

Micro and Nano Materials and Systems

Chairmen: Giancarlo Righini, Istituto di Fisica Applicata »Nello Carrara«, I
Roger Grace, Roger Grace Associates, USA

10:20 From MEMS to Smart Systems
Benedetto Vigna, STMicroelectronics, I

10:45 Electronic-Textile Platforms for Physiological and Psychological Monitoring
Rita Paradiso, SMARTX Srl, I

11:10 Optical sensor layers for amines and pH compatible with fabrication technologies
Gerhard Mohr, Fraunhofer IZM, D

11:35 Processing and Technology Development for MEMS Display Backplane
Kazuo Senda, Sumitomo Precision Product Co., Ltd., J

12:00 Smart Sensing Systems Integration: From Silicon to Plastic Foil
Danick Briand, EPFL, CH

EPoSS Session I

Excellence in Smart Systems Research

10:20 – 12:25

Invited speakers will present successful proposals initiated by EPoSS members in the framework of FP7 ICT Call 5. The following objectives of the current ICT Work Programme will be covered:

- Objective 3.9 »Microsystems and Smart Miniaturised Systems«
- Objective 1.3 »Internet of Things and Enterprise environments«
- Objective 10.3 »ICT for the Fully Electric Vehicle«

The special session by EPoSS, the poster presentations and the exhibition are free of charge for all participants, exhibitors and visitors.

LUNCH BREAK AND EXHIBITION

Session II

System Integration and Packaging II

Chairmen: Klaus-Dieter Lang, Fraunhofer IZM, D
Andreas Nebeling, ELMOS, D

13:45 Wafer-level Heterointegration Technologies for MEMS-based Communication Devices
Shuji Tanaka, Tohoku University, J

14:10 Highly integrated novel flow sensors
Christian Bosshard, CSEM, CH

14:35 Fabrication and integration of a new Micro Reactor Array for fluorescence analysis
Elisa Morganti, FBK-Fondazione Bruno Kessler, I

15:00 Precision photonic packaging using laser-based Solderjet Bumping
Thomas Burkhardt, Fraunhofer IOF, D

Session IV

Design of Smart Systems

Chairmen: Dag T. Wang, Sintef, N
Reinhard Neul, Robert Bosch GmbH, D

13:45 In-Process-Embedding of Piezo Sensors and RFID-Transponders into Cast Parts for Autonomous Manufacturing Logistics
Christoph Pille, Fraunhofer IFAM, D

14:10 Simulation, Measurement and Analysis of Electromagnetic Band Gap Structures for Noise Suppression in Electronic Systems
Ivan Ndiq, Fraunhofer IZM, D

14:35 Designing Smart Systems With Embedded Micro Features
David Topham, Arts & Science, UK

15:00 High Functional and Low Cost Antenna Solutions for the Internet of Things
Ralf Zichner, Fraunhofer ENAS, D

EPoSS Session II

Beyond FP7

13:45 – 15:15

This session will cover strategic topics in Smart Systems Integration such as

- Strategies towards FP8
- EPoSS Roadmaps 2013 and beyond
- The role of Smart Systems Integration in addressing major societal challenges
- Opportunities for international co-operation
- R&D and Standardization in Smart Systems Integration

OE-A Session:

Organic and Printed Electronics

Chairman:

Reinhard Baumann, Member of the OE-A Board, Fraunhofer ENAS, D

16:00 Printed RFID and Smart Systems – Status and Developments
Wolfgang Milder, PolyIC GmbH & Co. KG, D

16:30 Roll to Roll Printed 13.56 MHz Operated 16 bit RFID Tags
Gyou-Jin Cho, Sunchon National University, ROK

17:00 Equipment for Large Area Flexible Electronics and OPV
Thomas Kolbusch, Coatema Coating Machinery GmbH, D

17:30 Printable Electronic Materials: From lab to fab
Frank Meyer, Merck Chemicals Ltd, UK

18:00 Printing Electronics and State-of-the-Art Electronics Manufacturing
Markus Riemer, Maris TechCon, A

Organized by:



Wednesday, 24 March 2010

Keynote IV

8:45 hrs Smart electrical micro systems for treatment of Cardiac Arrhythmias and Heart Failure
Alain Ripart, Sorin Group, F

Keynote V

9:10 hrs Key Driver for Smart Systems Integration
Ryo Imura, Hitachi, J

COFFEE BREAK AND EXHIBITION

Session VIII

Advanced Micro and Nano Technologies

Chairmen: Mauro Varasi, Finmeccanica, I
Hugh Metras, CEA Léti, F

10:00 Femto- and picosecond laser micro processing of materials for MEMS and MOEMS on flexible and inflexible carriers – a comparison
Jens Hänel, 3D-Micromac AG, D

10:25 Integration of Organic Light Emitting Diodes into CMOS circuits for smart opto-electronic systems
Michael Scholles, Fraunhofer IPMS, D

10:50 Selective detection of toxic amines by combined resistive/surface ionization gas detectors
Carola Oberhütter, EADS Innovation Works Germany, D

11:15 Electret patterning technologies for microsystems
Vladimir Leonov, IMEC, B

11:40 UV Enhanced Full Field Wafer Scale Imprinting with Substrate Conformal Imprint Technique
Michael Hornung, SUSS MicroTec Lithography GmbH, D

Session IX

Diagnostic and Therapeutic Systems

Chairmen: Alain Ripart, Sorin Group, F
Markus Riemer, maris TechCon, A

10:25 System Integration of an Active Lens Implant
Liane Rheinschmitt, Karlsruhe Institut of Technology, D

10:50 Integrated Biosensor for label-free in-vitro DNA and protein diagnostics
Kari Tukkinemi, VTT Technical Research Center, FIN

11:15 A combination of low cost manufacturing, integrated sample preparation and ICT components to develop In Vitro Devices
Jesus Miguél Ruano-López, IKERLAN S. Coop., E

11:40 Self-contained microfluidic cartridges for in-vitro diagnostic applications: Recent advances and improvements
Jörg Nestler, Fraunhofer ENAS, D

Session X

Smart Systems for Automotive, Aeronautics and Food Transportation

Chairmen: André Perret, 4-Labs / CSEM, CH
Giorgio Grasso, Pirelli Labs, I

10:00 Smart monitoring system for aircraft structures
Vincent Rouet, EADS France-Innovation Works, F

10:25 Demonstrations of Wireless Autonomous Sensors for Aeronautical Applications
Pierre Nicole, Thales, F

10:50 Multi-parameter monitoring system for aviation hydraulic fluids
Sumit Paul, EADS Innovation Works Germany, D

11:15 Project IQFUEL
Bertrand Vayse, Continental Automotive France SAS, F

11:40 Contactless capacitive obstacle detection system for automotive applications
Johann Hauer, Fraunhofer IIS, D

LUNCH BREAK AND EXHIBITION

13:30 – 14:30 Poster Session and Coffee Break

The poster presenters will be available at their posters for questions and discussions. Details on all poster presentations are available at www.smartsystemsintegration.com/conference

Session XI

Reliability of Components and Systems

Chairmen: Matthias Kautt, Karlsruhe Institute of Technology, D
Bernd Michel, Fraunhofer ENAS, Fraunhofer IZM, D

14:30 Very high cycle fatigue of materials in modern small scale systems and applications
Christoph Eberl, Karlsruhe Institute of Technology, D

14:55 Investigation on Thermo-Mechanical Reliability of Flip-Chip Assemblies using Anisotropic Conductive Adhesive
Christine Kallmayer, Fraunhofer IZM, D

15:20 Combination of FE Simulation and Micro Deformation Measurements – a Promising Approach to Consider Reliability Aspects Right from the Start
Johann-Peter Sommer, Fraunhofer ENAS, D

15:45 Fault Tolerant ASIC Design for High System Reliability
Gunter Schoof, IHP GmbH, D

Session XII

Smart Sensornets and Communication Devices

Chairmen: Alessandro Bassi, Hitachi Europe, F
Chris van Hoof, IMEC, B

14:30 Designing low cost sensor systems for the Internet of Things
Andreas Schaller, ACS-Andreas Schaller Technology Consulting, D

14:55 Evolution of underlying technologies for networked smart systems: a prerequisite for the Internet of smart Things
Thomas Sommer, European Commission, B

15:20 Power optimization for wireless sensor nodes: Autonomous wireless muscle activity monitor powered by PV energy harvester
Valer Pop, Holst Centre, NL

15:45 A Resonance PLL-based Tracking System for Capacitive Sensors – MEMS/NEMS
Christopher Wiegand, Fraunhofer ENAS, D

Session XIII

Technical and Economical Trends

Chairmen: Karlheinz Bock, Fraunhofer IZM, D
Jean-Luc Maté, Euripides Office, F

14:30 Green car initiative
Pietro Perlo, Centro Ricerche Fiat, I

14:55 MEMS-based Systems Solutions: Selected Case Studies of Current and Emerging Applications
Roger Grace, Roger Grace Associates, USA

15:20 Research methods to assess the acceptance of electronic vehicles (EVs) – experiences from an EV user study
Josef Krebs, Technical University Chemnitz, D

15:45 Bringing Microsystems into Application: Application Center Smart System Integration - an example for efficient technology transfer
Harald Pötter, Fraunhofer IZM, D

MEMUNITY-Workshop

Wafer Level Testing for Fabrication of Intelligent Microsystems

10:00 EFM based methodology for dielectric charging characterization in MEMS
Antoine Nowodzinski, CEA Léti, F

10:20 Experimental characterization of BiCMOS embedded RF-MEMS devices
Kaynak Mehmet, IHP Frankfurt/Oder, D
10:40 Image based test methodology for laser display scanners
Hendrik Specht, Fraunhofer ENAS, D

11:00 Test of RF MEMS on wafer level
Stefan Leidich, Technical University Chemnitz, D

11:20 Presentation of a new 3D Nearfield Scanner System for the analysis of emission and immunity of electronic systems
Thomas Mager, Fraunhofer ENAS, D

11:40 Discussion

MEMUNITY-Workshop

Wafer Level Testing for Fabrication of Intelligent Microsystems

14:30 Employing Optical Measurement Techniques for MEMS on Wafer-Level
Christian Rembe, Polytec GmbH, D

14:50 Parameter Identification of Membrane Structures – Chances and Limitations
Steffen Michael, IMMS gGmbH, D

15:10 Wafer-level measurement solutions for devices characterization and reliability tests on next-generation semiconductor and emerging technologies
Sebastian Gießmann, SUSS MicroTec AG, D

15:30 Combined shear and creep test of soldered components on electronic boards
Walter Kammrath, Kammrath & Weiss GmbH, D

15:50 SMARTIEHS – a European Project for Parallel Testing of MIOIEMS
Steffen Michael, IMMS gGmbH, D

16:00 Discussion

Poster Sessions

Over 35 posters will be presented within the two poster sessions.

The poster presentations will take place on 23 March 2010 from 16:00 hrs – 17:00 hrs and on 24 March 2010 from 13:30 hrs – 14:30 hrs.

The poster exhibition is located in the exhibition area. The poster presenters will be available at their posters during the defined presentation hours for questions and discussions.

Poster presentations

Embedding Of Electronic And System In Package Using Added Manufacturing Technologies, Frank Ansoerge, Fraunhofer IZM - MMZ, D + **Theoretical study of a self-sustained CMOS-integrated nano-oscillator**, Gregory Arndt, CEA-Léti, F + **Miniaturization Potential of Micropump Electronics**, Thomas Baumann, Fraunhofer IZM, D + **A multi-gas detector module with built-in selftest functionality**, Sebastian Beer, EADS Innovation Works Germany, D + **Smart Communication in a Wired Sensor- and Actuator-Network of a Modular Robot Actuator System using a Hop-Protocol with Delta-Routing**, Stefan Bosse, University Bremen, D + **PCB stacked flip vias: process robustness and reliability tests results for harsh environment applications**, Michel Brizoux, THALES Corporate Services, F + **Thin film ultra-flexible multilayers for HDI industrial and medical systems**, Hans Burkard, Hightec MC AG, CH + **(Bio)Sensors’ system in Food Safety [BEST]**, Luigi Campanella, Università degli Studi di Roma La Sapienza”, I + **Photonic crystals as strain sensors**, Andrea Chiappini, CNR-IFN, I + **Nickel alloys electroforming as newroute for RF MEMS production**, Paula Cojocar, Politecnico di Milano, I + **Experimental Tests and Mathematical Models for Cutting Forces Evaluation in Micro-Milling**, Augusto M. De Filippi, Politecnico di Torino, I + **A Novel MEMS-based Multiparameter Sensor**, Massimiliano Decarli, FBK-Fondazione Bruno Kessler, I + **High frequency modeling of the impact of routing coplanar lines on glass substrates with periodically-arranged via structures**, Robert Erxleben, Fraunhofer IZM, D + **Strong and Energy-Efficient Micro-actuators for Smart Systems Integration**, Klas Hjort, Uppsala University, S + **Pulse Reverse Electroplating Methods for TSV Filling in 3D Integration**, Lutz Hofmann, Technical University Chemnitz, D + **A Method for the Fabrication of Extra-Thin Silicon Substrates**, Chenping Jia, Technical University Chemnitz, D + **Developing a distributed toolbox for advanced multimaterial micro and nano processing in Europe**, Matthias Kautt, Karlsruhe Institute of Technology, D + **Wafer Level Package with Simultaneous Y shaped- Through Wafer I/O Interconnection and Cavity Hermetic Sealing by Cu-Sn Isothermal Solidification for MEMS Resonator**, Le Luo, Shanghai Institute of Micro-system and Information Technology, CAS, CN + **Surface plasmon resonance optical biosensors multipurpose device**, Maria Grazia Manera, CNR-IMM LECCE, I + **Thermoelectric generators based on polymers and nanocomposites**, Joerg Martin, Fraunhofer ENAS, D + **Smart biocompatible glucose sensor using phospholipid polymer based enzyme-immobilization**, Kohji Mitsubayashi, Tokyo Medical and Dental University, J + **Monitoring intravascular pressure with a pulmonary artery pressure sensor system – assembly aspects**, Jutta Müntjes, RWTH Aachen, D + **Managing the Return-Currents of Signal Vias in Organic and Silicon Substrates**, Ivan Ndiq, Fraunhofer IZM, D + **Chip embedding into PCB’s - the iBoard Technology**, Alexander Neumann, Schweizer Electronic AG, D + **A novel plasma etching technique for notch-free structuring of SOI materials for MEMS applications**, Ha-Duong Ngo, Technical University Berlin, D + **High sensitive humidity sensors based on nanocomposites**, Doreen Piasta, Fraunhofer ENAS, D + **A multiparametric electrochemical microsensor for wine yeast quality assessment**, Cristina Ress, FBK-Fondazione Bruno Kessler, I + **Micro-multi-sensor platform for industrial processes monitoring**, Michel Saint-Mard, TAIPRO Engineering SA, B + **Squeeze Film Effect Based Micro Sensor for Vacuum Pressure Measurement**, Patrick Schwarz, University of Saarland, D + **Miniaturised Gas Chromatographic System for Ethylene Detection in Fruit Logistics**, Adam Sklorz, University Bremen, D + **Industrial applications of hybrid assembly for smart micro- and nano systems**, Alexander Steinecker, CSEM, CH + **A step by step methodological approach for merging FPGA dynamic reconfiguration and algorithm rapid designing tools**, Raul Torrego, IKERLAN S. Coop., E + **Stand-alone system for sepsis analysis**, Cosimo Trono, Istituto di Fisica Applicata »Nello Carrara«, I + **Printable ammonia gas sensor based on Polyaniline(PANI) and Polypyrrole(PPY)**, Cong Wang, Fudan University, CN + **Heterogeneous System Integration - A Key Technology for Future Micro-electronic Applications**, M. Jürgen Wolf, Fraunhofer IZM, D + **Effect of Array Periodicity on Filtering Characteristic for Metal/Dielectric Photonic Crystal**, Gongli Xiao, Fudan University, CN

20:30 – 23:00 CONFERENCE DINNER

Enjoy excellent food in the beautiful location of Villa Geno directly located at the shores of Lake Como. Network with other conference participants and speakers in a pleasant atmosphere. The announcement of the 1st SMART SYSTEMS INTEGRATION Award is part of the conference dinner. **The registration for the conference dinner is required due to limited space.** The busses to the Conference Dinner departure at 19:15 hrs.

Subject to change.

Best Paper Award / Best Poster Award

The Committee of SMART SYSTEMS INTEGRATION 2010 will award the Best Paper, selected by the committee, as well as the Best Poster, selected by the conference attendees and exhibition visitors. The nominated Best Papers are marked with a Ø.

Be part of it! Register now at www.smartsystemsintegration.com/conferenceregistration